

# IsoThermal™ Chamber Technology



*for Reflow Soldering and Curing Systems*

## Advanced Heating Chamber Technology

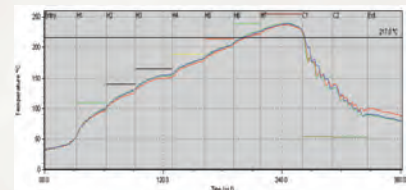
The OmniMax and OmniES incorporate IsoThermal Chamber Technology (ICT). This is an advanced, efficient heating chamber design that provides maximum thermal performance. Electrovert's innovative approach to thermal transfer delivers highly efficient heat transfer throughout the entire process and product. Consistent thermal performance of the ICT promotes excellent zone separation, minimizes cross board  $\Delta T$ 's and allows for better control of time above liquidus (TAL).

## Features

- Precise control of convection dynamics
- Heat-on-intake technology
- Delivers highly efficient heat transfer throughout the entire process and product
- Well-defined transitions between each heating zone

## Benefits

- Constant temperatures across the entire PCB
- Highly repeatable profiles under load conditions
- Reduced power and nitrogen consumption
- Excellent separation between heating and cooling for better TAL



## Available Configurations:

- OmniMax 7 and 10 zones
- OmniES 7 and 10 zones
- ICT combined with a comprehensive list of OmniMax and OmniES technologies offers the total solution

